

[SCRIBE LINE STRUCTURE OF WAFER]

Abstract

A wafer scribe line structure is provided. A plurality of lump patterns is set up to fill the entire scribe line area so that the amount of stress the wafer is subjected to during a dicing process is reduced, thereby reducing the probability of having a delamination at the interface of wafer layers. Moreover, the lump patterns can be formed simultaneously with metal interconnects in a metal interconnect process.